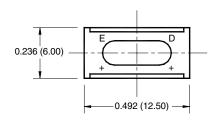
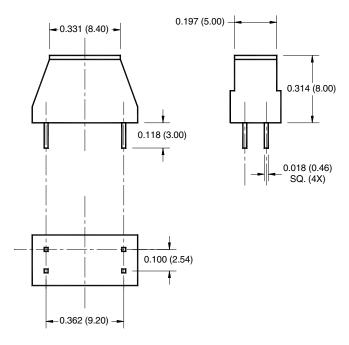
## **PACKAGE DIMENSIONS**



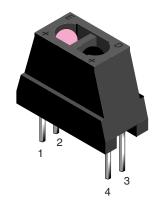


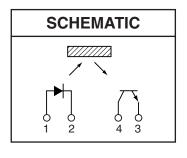
### NOTES:

- 1. Dimensions for all drawings are in inches.
- 2. Tolerance of ± .010 on all non-nominal dimensions unless otherwise specified.

## **FEATURES**

- Phototransistor output
- No contact surface sensing
- Daylight filter on the sensor
- Emitter  $\lambda = 940 \text{ nm}$







ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise specified)								
Parameter	Symbol	Rating	Units					
Operating Temperature	T <sub>OPR</sub>	-40 to +85	°C					
Storage Temperature	T <sub>STG</sub>	-40 to +85	°C					
Soldering Temperature (Iron)(2,3,4)	T <sub>SOL-I</sub>	240 for 5 sec	°C					
Soldering Temperature (Flow)(2,3)	T <sub>SOL-F</sub>	260 for 10 sec	°C					
EMITTER		50	mA					
Continuous Forward Current	l <sub>F</sub>	30						
Reverse Voltage	V <sub>R</sub>	5	5 V					
Peak Forward Current	I <sub>FP</sub>	1	A					
Power Dissipation <sup>(1)</sup>	P <sub>D</sub>	100	mW					
SENSOR	V	30	V					
Collector-Emitter Voltage	V <sub>CEO</sub>	30						
Power Dissipation <sup>(1)</sup>	P <sub>D</sub>	100	mW					

ELECTRICAL / OPTICAL CHARACTERISTICS (T <sub>A</sub> = 25°C)								
PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS		
EMITTER	I- 00 m A	VF	_	_	1.7	٧		
Forward Voltage	IF = 20 mA							
Reverse Current	$V_R = 5 V$	$I_{R}$	_	_	100	μΑ		
Peak Emission Wavelength	IF = 20 mA	$\lambda_{PE}$	_	940	_	nm		
SENSOR	V 40.V 1 0 A				100			
Dark Current	$V_{CE} = 10 \text{ V}, \text{ If } = 0 \text{ mA}$	lp	_		100	nA		
Peak Sensitivity Wavelength	Vce = 5 V	$\lambda_{PS}$	_	880	_	nm		
COUPLED	1 00 1 10 1/07	Ic(on)	0.16	_	2.00	mA		
Collector Current	$I_F = 20 \text{ mA}, V_{CE} = 10 V^{(6,7)}$							
Collector Emitter	$I_F = 20 \text{ mA}, I_C = 0.5 \text{ mA}$	VCE (SAT)	_	_	0.4	V		
Saturation Voltage								
Rise Time	$V_{\text{CE}}$ = 5 V, $R_{\text{L}}$ = 100 $\Omega$	tr	<u> </u>	10	<u> </u>	μs		
Fall Time	$I_{C(ON)} = 5 \text{ mA}$	<b>t</b> f		50	_	μs		

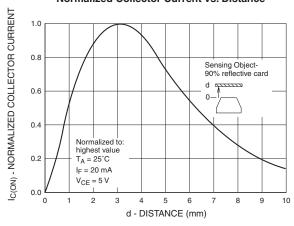
## **NOTES**

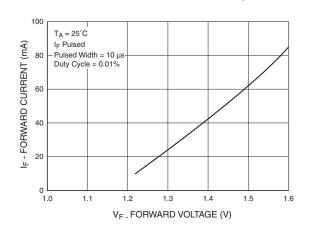
- 1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron tip at 1/16" (1.6mm) from housing.
- 5. Pulse conditions:  $tp = 10 \mu s$ ; T = 1 ms.
- 6. Measured as an Eastman Kodak neutral white test card with 90% diffused reflectance as a reflecting surface.
- 7. 0.160" (4 mm) distance from sensor face to reflector surface.



## **TYPICAL PERFORMANCE CURVES**

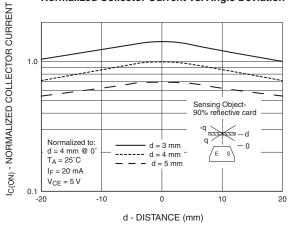
### Normalized Collector Current vs. Distance



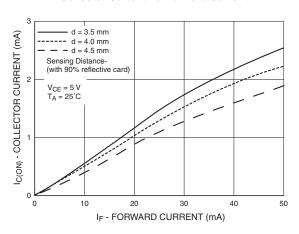


Forward Current vs. Forward Voltage

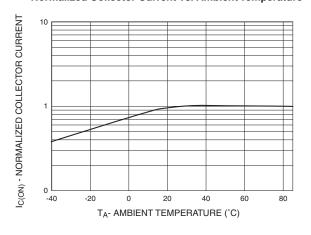
#### Normalized Collector Current vs. Angle Deviation



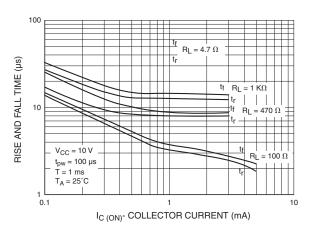
#### Collector Current vs. Forward Current



## Normalized Collector Current vs. Ambient Temperature



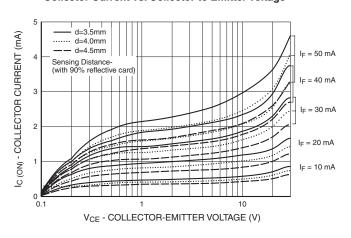
### Rise and Fall Time vs. Collector Current



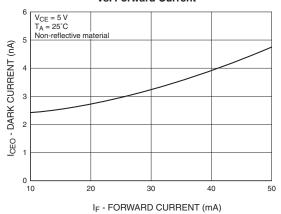


## **TYPICAL PERFORMANCE CURVES**

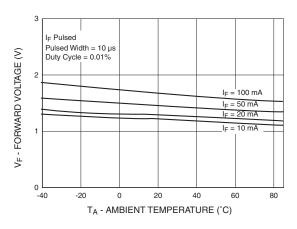
### Collector Current vs. Collector to Emitter Voltage



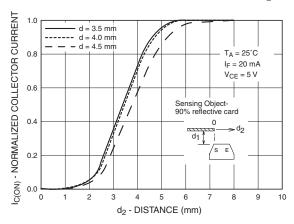
## Collector Emitter Dark Current vs. Forward Current



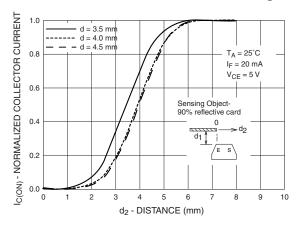
#### Forward Voltage vs. Ambient Temperature



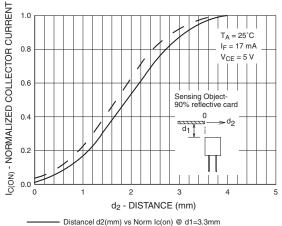
#### Normalized Collector Current vs. Distance d2



### Normalized Collector Current vs. Distance d<sub>2</sub>

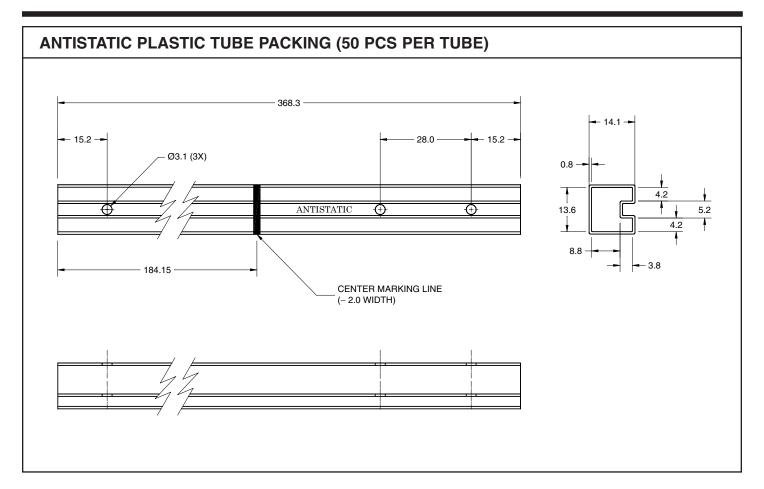


### Normalized Collector Current vs. Distance d<sub>2</sub>



- - - Distancel d2(mm) vs Norm Ic(on) @ d1=4.5mm





## **NOTES**

- 1. Dimensions: All dimensions are in mm.
- 2. Color: Clear (Transparent).
- 3. Antistatic resistivity level:  $10^5$   $10^{12}$  Ohm/sq.
- 4. Tolerance: ±0.25 inches, unless otherwise specified.



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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.